

# Precautions of Bonder

1. The surface of the wafer must consist of an oxide layer or another insulating layer, rather than a metal layer or organic material, and it should be free of any surface peeling.
2. Please ensure that the wafer is free of any bending, as this may cause it to break during the bonding process.
3. The bonding of different substrate materials should avoid the annealing process to prevent wafer cracking after annealing.
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